

IMPACT

TE Internal #: 2007777-2

High Speed Backplane Connectors, 90 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 10 Column, PCB Mount

Header, Vertical, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board

Number of Positions: 90

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Keyed

Features

Product Type Features

Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Ground Positions	30
Number of Pairs	30
Stackable	No
Number of Signal Positions	60
Number of Positions	90
Number of Rows	9
Number of Columns	10
PCB Mount Orientation	Vertical
Guide Location	Left

Electrical Characteristics

Impedance	100 Ω
Operating Voltage	30 VAC



Signal Characteristics	
Number of Differential Pairs per Column	3
Data Rate	20 – 25 Gb/s
Body Features	
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	4.9 mm[.193 in]
PCB Contact Termination Area Plating Material Thickness	.76 – 1.52 μm[30 – 60 μin]
Contact Layout	Inline
Contact Type	Pin
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	.76 μm[29.92 μin]
Contact Mating Area Plating Material	Gold
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Dual Beam
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A
Termination Features	
Termination Post & Tail Length	1.4 mm[.055 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Guide Hardware	Without
Mating Retention	Without
PCB Mount Retention	With
PCB Mount Retention Type	Action/Compliant Tail & Screw
Mating Alignment	With
Mating Alignment Type	Keyed
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2



End Wall Location	Open
Housing Material	LCP - GF (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	25.5 mm[1.004 in]
Connector Height	24.6 mm[.969 in]
Connector Width	16.7 mm[.657 in]
PCB Thickness (Recommended)	1 mm
PCB Hole Diameter	.39 mm[.015 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
	-55 – 85 °C[-67 – 185 °F]
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F] Signal
Operating Temperature Range Operation/Application	
Operating Temperature Range Operation/Application Circuit Application	
Operating Temperature Range Operation/Application Circuit Application Industry Standards	Signal
Operating Temperature Range Operation/Application Circuit Application Industry Standards Approved Standards	Signal CSA Certified, UL E28476
Operating Temperature Range Operation/Application Circuit Application Industry Standards Approved Standards UL Flammability Rating	Signal CSA Certified, UL E28476

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability



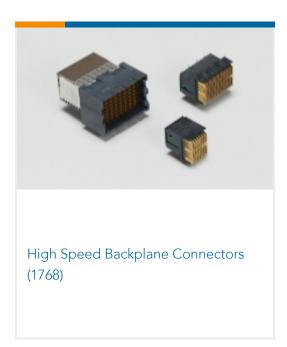
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | IMPACT



Customers Also Bought











TE Part #1616005-8

B452=RELAY

TE Part #72526-09-35PN

HERM RECP

Documents

Product Drawings

IMP100S,H,V3P10C,LG,OEW39,4.9

English

CAD Files

Customer View Model

ENG_CVM_CVM_2007777-2_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2007777-2_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2007777-2_B.3d_stp.zip

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English

Agency Approvals

Agency Approval Document

English